ABSTRACT

In a substrate transfer apparatus, an inner surface of a protective cover is covered with a cover protection means when the substrate is being used. Therefore, the inner surface of the protective cover can be prevented from being contaminated when the substrate is being used. Further, the protective cover is grounded at a standby position. Therefore, the protective cover is prevented from being electrostatically charged and adhesion of particles on the protective cover is reduced. In the substrate transfer method, the protective cover is permitted to wait in a condition where the inner surface of the protective cover is being covered when the substrate is being used. Therefore, the inner surface of the protective cover can be prevented from being contaminated. In an exposure apparatus, since the substrate transfer apparatus is used, a product can be obtained at a high yield by using the less contaminated substrate.